

To: **Technology Center 2800**  
**Attn: Vikki Short**  
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**NOTE: Ms. Short, per your request, attached is a copy of the Notice of Appeal that was mailed to the USPTO on August 12, 2003.**

From: **Michael K. Skrehot**  
**Texas Instruments Incorporated**  
**Facsimile: 972-917-4417**  
**Phone: 972-917-5653**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**In re the Application of: **Gonzalo Amador, et al.**Docket Number: **TI-30592**Serial No.: **09/817,694**Art Unit: **2823**Filed: **03/26/2001**Examiner: **Toledo, Fernando**

For: **Fixture and Method for Uniform Electroless Metal**  
**Deposition on Integrated Circuit Bond Pads**

Conf. No.: **9346****CERTIFICATION OF FACSIMILE TRANSMISSION**

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at (703) 746-8825 on the date shown below:

  
Elizabeth AustinDate: **10/28/2003****FACSIMILE COVER SHEET**

<input checked="" type="checkbox"/> <b>FACSIMILE COVER SHEET</b>	<input type="checkbox"/> <b>AMENDMENT</b> ( Pages)
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<input type="checkbox"/> <b>CONTINUATION APP'N</b> ( Pages)	
<input type="checkbox"/> <b>DIVISIONAL APP'N</b>	
<b>NAME OF INVENTOR(S):</b> <b>Gonzalo Amador, et al.</b>	
<b>RECEIPT DATE &amp; SERIAL NO.:</b> <b>09/817,694</b>	
<b>TITLE OF INVENTION:</b> <b>Fixture and Method for Uniform Electroless Metal Deposition on Integrated circuit Bond Pads</b>	
<b>FILING DATE:</b> <b>03/26/2001</b>	
<b>TI FILE NO.:</b> <b>TI-30592</b>	<b>DEPOSIT ACCT. NO.:</b> <b>20-0668</b>
<b>DATE FAXED:</b> <b>October 28, 2003</b>	
<b>DUE:</b> <b>August 12, 2003</b>	
<b>ATTY/SECY:</b> <b>Michael Skrehot / E. Austin</b>	

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Gonzalo Amador, et al.

TI No.: 30592

Serial No.: 09/817,694

Art Unit: 2823


Filed: 03/26/2001

Examiner: Toledo, Fernando

For: Fixture And Method For Uniform Electroless  
Metal Deposition On Integrated Circuit Bond  
Pads

Conf. No.: 9346

NOTICE OF APPEALCommissioner For Patents  
Alexandria, VA 22313-1450

<b>MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)</b>	
I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450	
 Elizabeth Austin	8/12/2003 Date

Sir:

Applicant hereby appeals to the Board of Appeals from the decision dated May 12, 2003, of the Primary Examiner finally rejecting Claims 1-5, 12, 16 and 17.

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

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Respectfully submitted,

Michael K. Skrehot  
Attorney for Applicant  
Reg. No. 36,682

In The "Received" stamp of the Patent and Trademark Office imprinted hereon acknowledges the filing of:

<input type="checkbox"/> NEW APPLICATION TRANSMITTAL <input type="checkbox"/> DECLARATION - <input type="checkbox"/> ASSIGNMENT & RECORDATION COVER SHEET <input type="checkbox"/> FORMAL DRAWINGS ( SHEETS ENCLOSED) <input type="checkbox"/> CONTINUATION APPLICATION <input type="checkbox"/> DIVISIONAL APPLICATION <input type="checkbox"/> ISSUE FEE & LETTER OF TRANSMITTAL	<input type="checkbox"/> AMENDMENT - _____ ( _____ pages) <input type="checkbox"/> AMENDMENT FEE TRANSMITTAL <input type="checkbox"/> EOT - _____ MONTH(S) <input checked="" type="checkbox"/> NOTICE OF APPEAL <input type="checkbox"/> APPEAL BRIEF <input type="checkbox"/> REPLY BRIEF ( IN TRIPLICATE )
NAME OF INVENTOR(S): Gonzalo Amador and Roger J. Stierman	SERIAL NUMBER: 09/817,694
TITLE OF INVENTION: Fixture And Method For Uniform Electroless Metal Deposition On Integrated Circuit Bond Pads	CONFIRMATION NO.: 9346
TI FILE NO.: TI-30592      DEPOSIT ACCT. NO.: 20-0668	
EXPRESS MAIL RECEIPT NO.:	
MAILED DATE: August 12, 2003	
DATE DUE: August 12, 2003	
ATTY/SEC'Y: Michael Skrehot / E. Austin	